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11002 U.S. PTO  
10/099861  
03/15/02

PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10099861	FILING DATE 03/15/2002	CLASS 420	SUBCLASS 7	GAU 1742	EXAMINER J. Smith
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\*\*APPLICANTS: Yeh Shing; Carter Bradley; Melcher Curtis;

JC 1117

\*\*CONTINUING DATA VERIFIED:

\*\* FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials			☐ yes ☐ no ☐ yes ☐ no
ATTORNEY DOCKET NO DP-305031			
TITLE : Lead-free solder alloy and solder reflow process			

U.S. DEPT. OF COMM./PAT. & TM-PTO-435L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drawg.	Figs. Drawg.	Print Fig.
TERMINAL DISCLAIMER		Primary Examiner		
		PREPARED FOR ISSUE		
		Application Examiner		
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